

Material Declaration Report

Package Type:	TQFN 16L (3x3mm)
Pericom Package Code:	ZH16(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	20.4330
Termination Plating:	Matte Sn
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10~20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	30
Reflow Cycles:	3
Rev Date:	3/8/2010

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	8.8820		Silica fuse Epoxy resin Phenol resin Carbon black	60676-86-0 Proprietary Proprietary 1333-86-4	90.500 4.500 4.500 0.500	8.0382 0.3997 0.3997 0.0444
LEADFRAME	5.8783		Copper Iron Zinc Phosphorus Silver	7440-50-8 7439-89-6 7440-66-6 7723-14-0 7440-22-4	97.021 2.350 0.111 0.065 0.453	5.7032 0.1381 0.0065 0.0038 0.0266
SILICON DIE	0.8120		Silicon (Si) Non-hazardous Metal	7440-21-3 Proprietary	99.192 0.808	0.8054 0.0066
DIE ATTACH EPOXY	1.5910	UTL SPEL	Silver Acrylate Resin Heterocyclic organic compound Treated Silica Silver Epoxy Resin Diluent Dicyandiamide Hardener	7440-22-4 Proprietary Proprietary 7631-86-9 7440-22-4 9003-36-5 26447-14-3 461-58-5 620-92-8	80.000 16.000 2.000 2.000 80.000 10.000 6.000 0.500 3.500	1.2728 0.2546 0.0318 0.0318 1.2728 0.1591 0.0955 0.0080 0.0557
GOLD WIRE	1.8162		Gold(Au) Impurities	7440-57-5 -	99.990 0.010	1.8160 0.0002
SOLDER PLATING	1.4535		Tin (Sn) Impurity	7440-31-5 -	99.990 0.010	1.4534 0.0001

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Leadframe	<50	<2	<2	<2	<5	<5
Device Silicon Die	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Plating	<50	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006	Declaration Statement:	Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium					
		Pb <1000ppm	Hg <1000ppm	Cr+6 <1000ppm	Cd <100ppm	PBB <1000ppm	PBDE <1000ppm
		O	O	O	O	O	O

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.
X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.